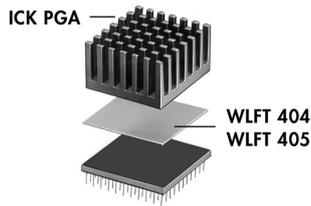


## Data sheet Product ICK PGA 14 x 14 x 10



Heatsinks and active heatsinks for processors>Heatsinks for PGA  
35 x 35 x 10 mm, for IC design PGA and others

### Features

way of fixation:	<ul style="list-style-type: none"> <li>• therm. conductive foil</li> <li>• therm. cond. adhesive</li> </ul>
socket:	universal
suitable for processor type:	universal
width:	36 mm
height:	12.3 mm
plate thickness:	3.5 mm
length:	36 mm
thermal resistance:	10.5 - 3 K/W
dissipation loss:	11.2 W
surface:	black anodised

### Technical Drawing

